

STM32WL_BGA73_IPD_4Layers_IPD_TX_HighPower

MB1849_HP

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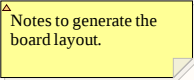
- Sheet 1: Project overview (this page)
- Sheet 2 : STM32WL_BGA73_RefBoard_IPD_HP.SchDoc

Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



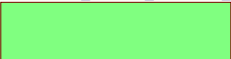
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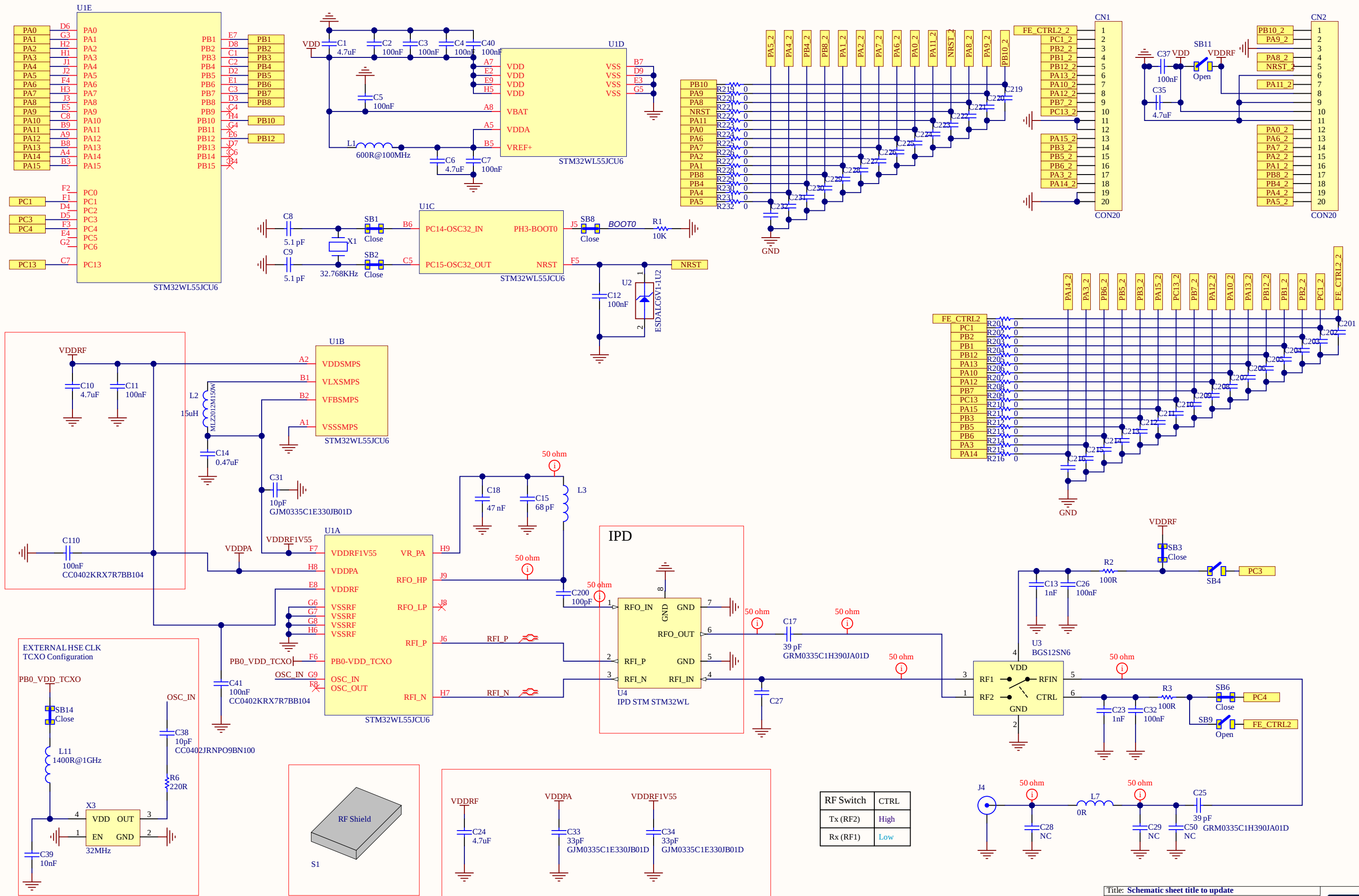
U_Top
STM32WL_BGA73_RefBoard_IPD_HP.SchDoc

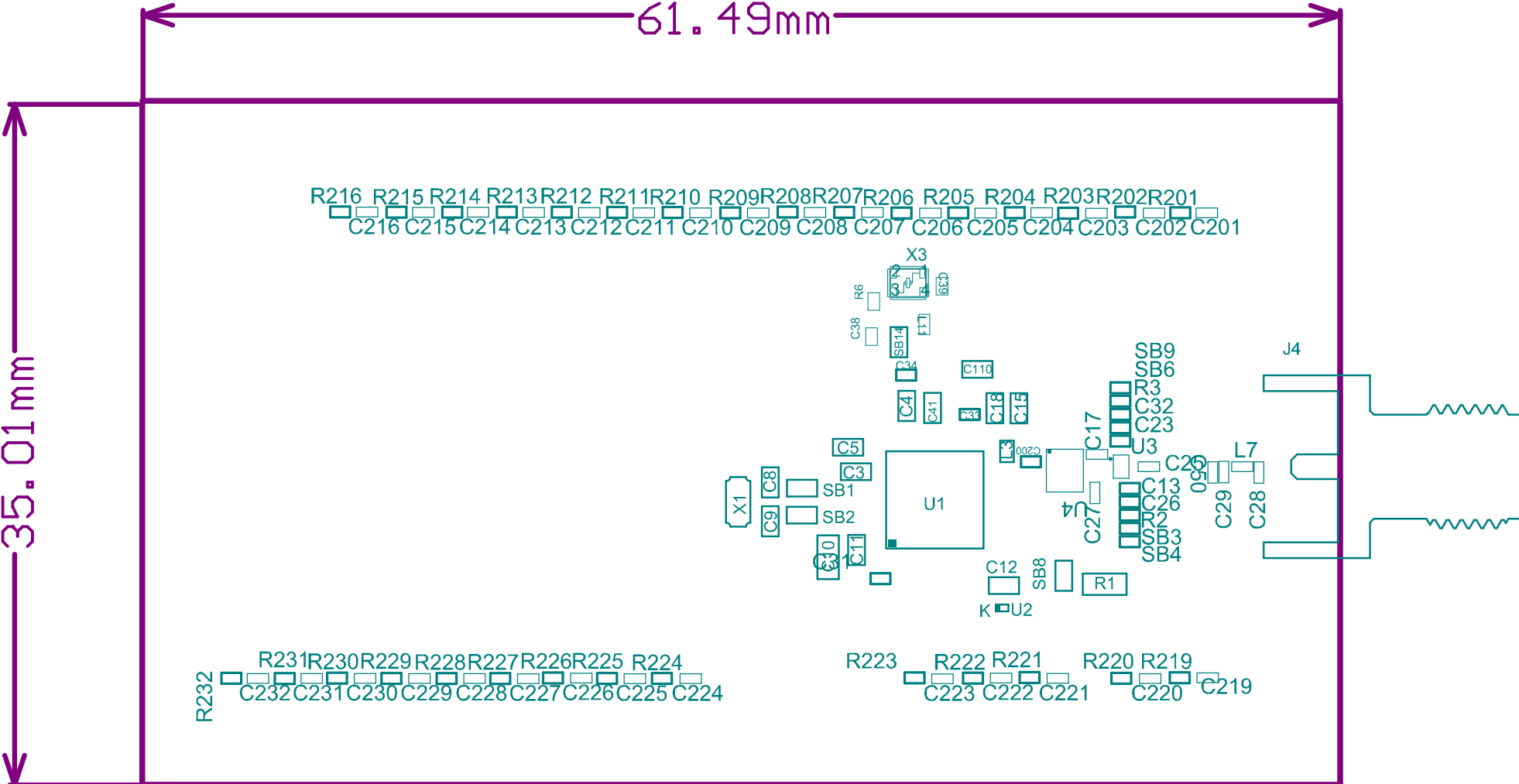


Title: Schematic sheet title to update		
Project: STM32WL_BGA73_IPD_4Layers_IPD_TX_HighPower		
Variant: [No Variations]		
Revision: A-01	Reference: MB1849_HP	
Size: A4	Date: 20/06/2022	Sheet: 1 of 2

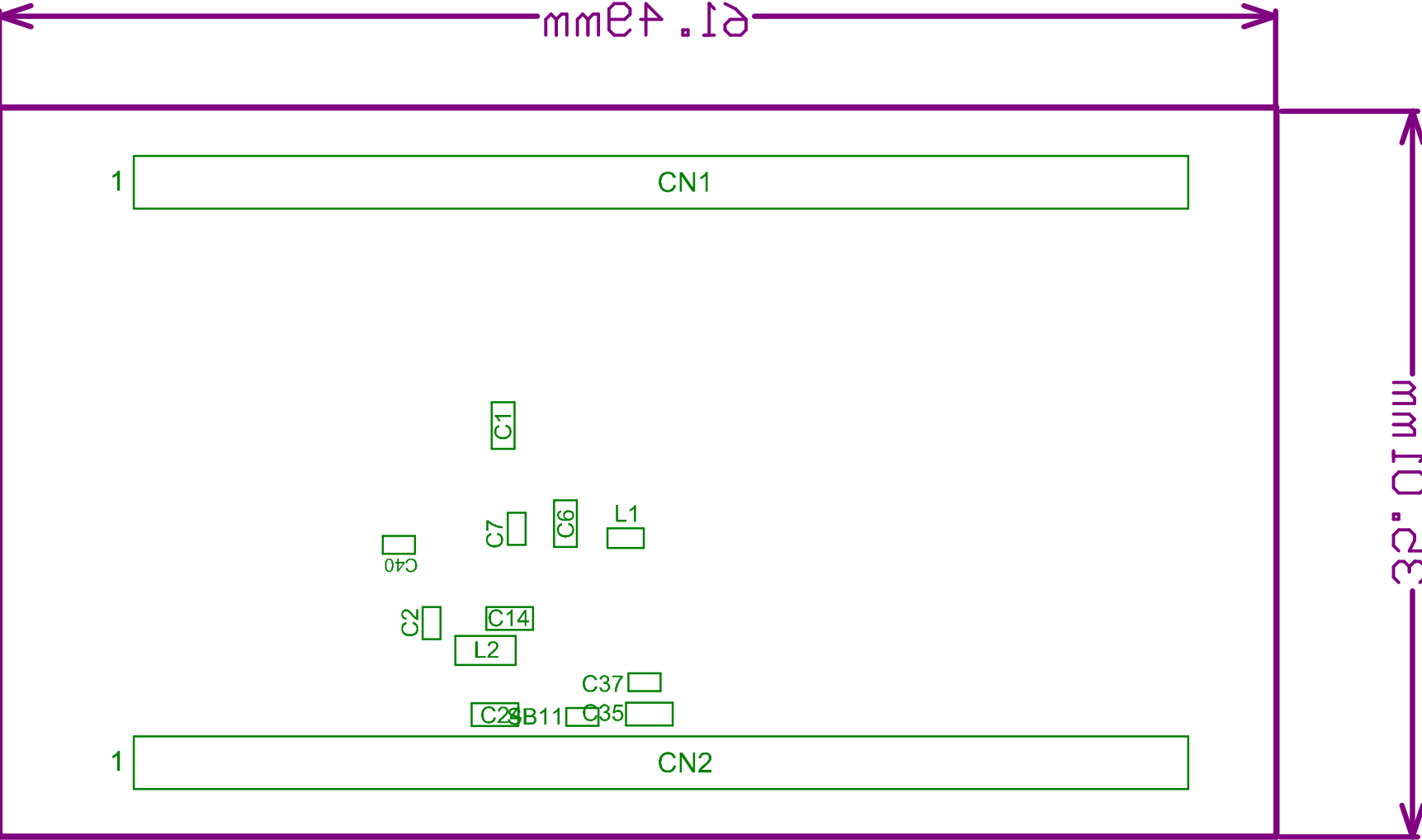


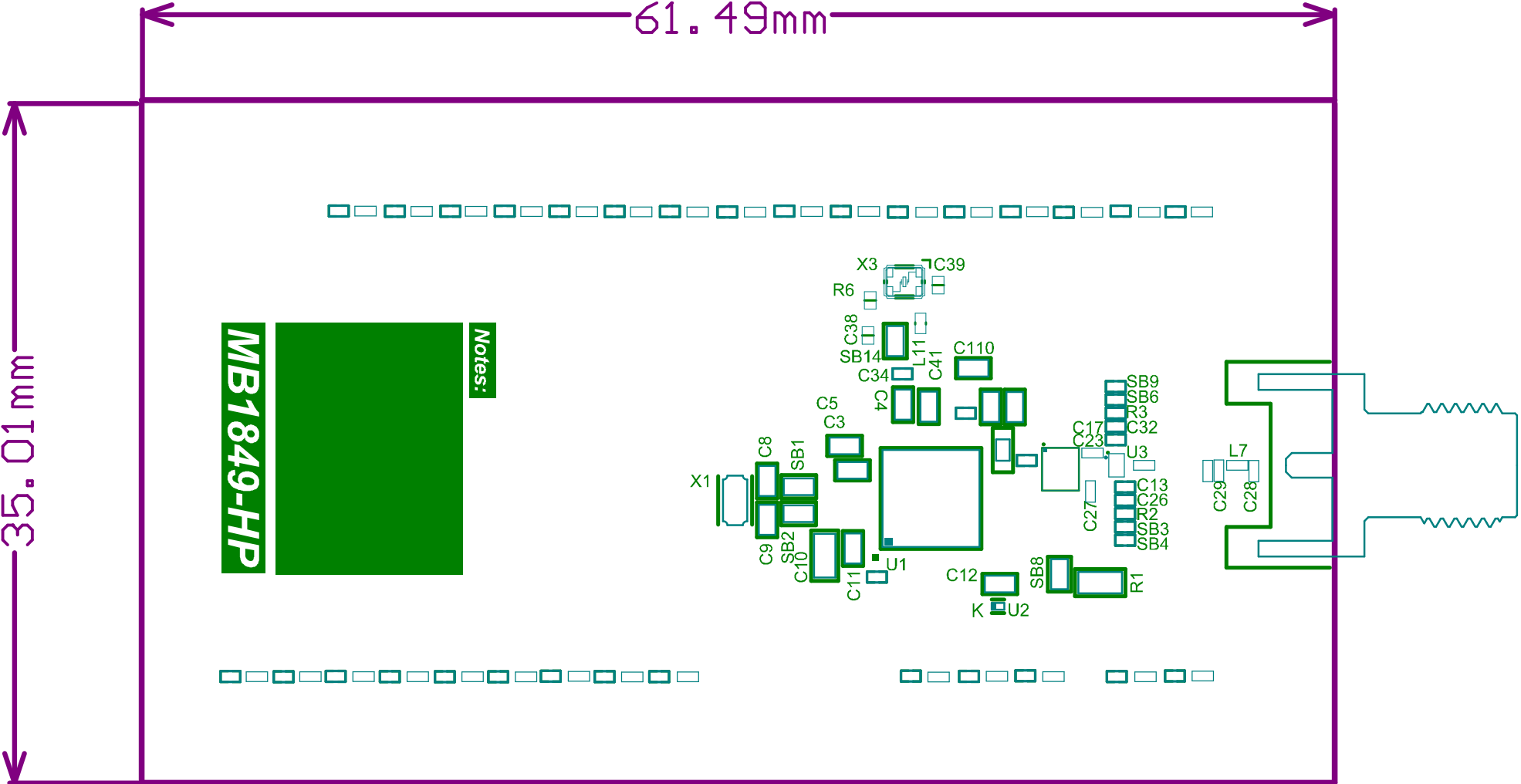
STM32WL BGA IPD - High Power Mode - Reference Board





Project: STM32WL_BGA73_IPD_4Layers_IPD_TX_HighPower		
Layer: Top Assembly	Gerber: .GM14	
Variant: [No Variations]	Ref: MB1849_HP	
Date: 20/06/2022	Rev: A	





Top Assembly

.G104

